Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	60	@ad<="20031022" and 'embedded' with 'capacitor' same 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:33
L2	12	@ad<="20031022" and 'embedded' with 'capacitor' same 'PCB' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:59
L3	12	@ad<="20031022" and 'embedded' with 'capacitor' and 'PCB' and 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:04
L6	2568	@ad<="20031022" and 'dielectric constant' with 'polyimide'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:48
L7	5	@ad<="20031022" and 'dielectric' and 'PDF' and 'PZT'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:49
L8	263	@ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:55
L9	1	@ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT' and 'FR-4'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:49
L10	9	@ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:51
L11	1	"5656834".PN.	USPAT; USOCR	OR	ON	2005/07/05 08:52
L12	1	"5347258".PN.	USPAT; USOCR	OR	ON	2005/07/05 08:52
L13	1	"5261153".PN.	USPAT; USOCR	OR	ON	2005/07/05 08:53
L14	1	"5162977".PN.	USPAT; USOCR	OR	ON	2005/07/05 08:53
L15	37	@ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:58

L16	0	@ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT' and 'wiring board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 08:58
L17	4	@ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT' and 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:21
L18	10	(("6349456") or ("5079069") or ("5261153") or ("5800575") or ("6274224")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/05 09:33
L20	72	@ad<="20031022" and 'embedded capacitor' same 'printed circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 10:22
L21	1	"5656834".PN.	USPAT; USOCR	OR	ON	2005/07/05 10:27
S1	722	@ad<="20031022" and 'PCB' and 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:09
S2	71	@ad<="20031022" and 'PCB' and 'signal trace' and 'low impedance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 08:49
S3	140	@ad<="20031022" and 'differential' with 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:59
S4	49	@ad<="20031022" and 'PCB' and 'differential' with 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:12
S5	1	"6005895".PN.	USPAT; USOCR	OR	ON	2005/01/12 08:59
S6	1	"5956518".PN.	USPAT; USOCR	OR	ON	2005/01/12 09:00
S7	7	@ad<="20031022" and 'copper trace' same 'coupling' same 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:21

S8	70	@ad<="20031022" and 'copper' with 'high dielectric' same 'low dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:42
S9	115	@ad<="20031022" and 'interconnection' and 'copper layer' and 'high dielectric' and 'low dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 09:42
S10	13	@ad<="20031022" and 'differential' with 'signal line' and 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:29
S11	735	@ad<="20031022" and (257/664-665).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:17
S12	585	@ad<="20031022" and 'differential signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:48
S13	44	@ad<="20031022" and 'differential signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:30
S14	51	@ad<="20031022" and 'differential signal line' same 'coupling'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:45
S15	3	@ad<="20031022" and 'differential signal line' same 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:50
S16	24	@ad<="20031022" and 'PCB' and 'differential signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 10:50
S17	1	'PCB' and 'base layer' and 'ground plane' and 'stripline'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:00
S18	356	'PCB' and 'stripline'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:00

S19	320	'PCB' and 'stripline' and 'signal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:28
S20	1	"6201194".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:03
S21	1	"6175087".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:04
S22	1	"6171946".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:06
S23	1	"6026564".PN.	USPAT; USOCR	OR	ON	2005/01/12 11:07
S24	245	'PCB' and 'stripline' and 'signal' and 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:10
S25	20	'PCB' and 'stripline' and 'signal' and 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:10
S26	10	'Electromagnetic coupler circuit board'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:29
S27	356	'Electromagnetic coupler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:31
S28	217	'Electromagnetic coupler' and 'signal'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:40
S29	38	'Electromagnetic coupler' and 'signal line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:43
S30	102	'Electromagnetic' with 'coupling' and 'signal trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 11:58
S31	4915	'Electromagnetic' with 'coupling' and 'dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:02

S32	497	'Electromagnetic' with 'coupling' and ' high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:03
S33	20	'PCB' and 'Electromagnetic' with 'coupling' and ' high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:03
S34	1685	@ad<="20031022" and (257/734-736).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:07
S35	1483	@ad<="20031022" and (257/700). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:07
S36	1105	@ad<="20031022" and (257/750). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:34
S37	879	@ad<="20031022" and (257/762). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:08
S38	648	@ad<="20031022" and (257/211). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 12:08
S39	2	("0691193").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 12:17
S40	2	("6449308").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:07
S41	7	(("3615951") or ("6705895")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/12 13:07

S42	27	@ad<="20031022" and 'PCB' same 'FR4' same 'resin' same 'fiber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:36
S43	96	@ad<="20031022" and 'FR4' with 'resin' with 'fiber'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/12 13:36
S44	1	"20050087877"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:33
S45	30	@ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 15:21
S46	1	@ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler' with 'polyvinylidene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:42
S47	19	@ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:24
S48	0	@ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:25
S49	0	@ad<="20031022" and 'coper' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S50	0	@ad<="20031022" and 'coper' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S51	0	@ad<="20031022" and 'PCB' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:44
S52	107	@ad<="20031022" and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 14:47

S53	21	@ad<="20031022" and 'dielectric' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:04
S54	69	@ad<="20031022" and 'FR4' and 'copper' with 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/28 15:21
S55	25	@ad<="20031022" and 'circuit board' and 'trace' with 'high dielectric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:15
S56	1	"4967314".PN.	USPAT; USOCR	OR	ON	2005/04/29 08:17
S57	2	@ad<="20031022" and 'trace' with 'high dielectric' same 'solder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:15
S58	150	@ad<="20031022" and 'PCB' and 'signal trace' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:39
S59	11	@ad<="20031022" and 'PCB' and 'signal trace' with 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:18
S60	71	@ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:48
S62	0	@ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask' and 'high k'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 09:48
S63	4	Han-Dong-Ho.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 10:18
S64	18	@ad<="20031022" and 'trace' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:09

S65	338	@ad<="20031022" and 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:57
S66	0	@ad<="20031022" and 'solder mask' same 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:10
S67	5	@ad<="20031022" and 'PCB' and 'copper' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
S68	0	@ad<="20031022" and 'PCB' and 'copper' and 'filler' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
S69	153	@ad<="20031022" and 'filler' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:17
S70	0	@ad<="20031022" and 'copper' same 'fille' with ('polyvinylidene diflouride' or pvdf)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/29 11:18
S71	321	@ad<="20031022" and 'PCB' same 'filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:02
S72	49	@ad<="20031022" and 'PCB' same 'filler' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 14:53
S73	1	"4361634".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:25
S74	1	"5150088".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:27
S75	1	"5185502".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:28
S76	1	"5185502".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:30
S77	1	"5278524".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:31
S78	1	"5278524".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:32
S79	1	"5677515".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:32

S80	1	"5719750".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:33
S81	1	"6072690".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:33
S82	1	"4567542".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:33
S83	1	"5400210".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:39
S84	1	"5378662".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:39
S85	1	"5371403".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:39
S86	1	"5177670".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:39
S87	1	"5027253".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:43
S88	1	"4999520".PN.	USPAT; USOCR	OR	ON	2005/07/01 14:43
S89	2	("5133120").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/01 14:54
S90	0	@ad<="20031022" and 'photo solder resist' with 'dielectric constant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:03
S91	0	@ad<="20031022" and 'dilelectric constant' with 'photo solder resist'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:03
S92	19	@ad<="20031022" and 'solder resist' with 'dielectric constant'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:10
S93	0	@ad<="20031022" and 'dilelectric constant' with 'solder resist'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:03
S94	1	@ad<="20031022" and 'impedance' same 'insulative' and 'solder resist' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:14
S95	70	@ad<="20031022" and 'impedance' same 'insulative' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:17

S96	43	@ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'impedance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:18
S97	157	@ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:45
S98	4	@ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'filler' and 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/01 15:18
S99	7	@ad<="20031022" and 'PRINTED WIRING BOARD' same 'dielectric filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 06:35
S10 0	2	("5162997").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/04 06:30
S10 1	1	"4306273".PN.	USPAT; USOCR	OR	ON	2005/07/04 06:32
S10 2	3	@ad<="20031022" and 'wiring board' and 'trace' with 'permittivity'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 06:39
S10 3	554	@ad<="20031022" and 'wiring board' same 'capacitance'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 06:40
S10 4	3	@ad<="20031022" and 'wiring board' same 'capacitance' and 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 06:47
S10 5	17	@ad<="20031022" and 'PCB' same 'capacitance' and 'solder mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 06:47
S10 6	17	@ad<="20031022" and 'PCB' same 'discrete' same 'signal path'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:01

S10 7	26	@ad<="20031022" and 'PCB' and 'trace' with 'filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:27
S10 8	4	(("5162144") or ("5260170")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/04 07:12
S10 9	1	"4590115".PN.	USPAT; USOCR	OR	ON	2005/07/04 07:19
S11 0	1	"4565606".PN.	USPAT; USOCR	OR	ON	2005/07/04 07:19
S11 1	91	@ad<="20031022" and 'FR-4' and 'discrete' same 'trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:28
S11 2	75	@ad<="20031022" and 'FR-4' and 'discrete' with 'trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:28
S11 3	75	@ad<="20031022" and 'FR-4' and 'trace' with 'discrete'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:28
S11 4	13	@ad<="20031022" and 'FR-4' and 'discrete' with 'trace' and 'mask'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:42
S11 5	13	@ad<="20031022" and 'FR-4' and 'capacitance' and 'dielectric filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:49
S11 6	12	@ad<="20031022" and 'PCB' and 'capacitance' and 'dielectric filler'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 07:49
S11 8	641	@ad<="20031022" and 'copper' with 'polyvinylidene'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:39
S11 9	29	@ad<="20031022" and 'copper' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:38

S120	1	@ad<="20031022" and 'lead titanate' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:33
S121	2	@ad<="20031022" and 'lead titanate' and 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:37
S122	0	@ad<="20031022" and 'dielectric constant' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:37
S123	6	@ad<="20031022" and 'dielectric' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:37
S124	0	@ad<="20031022" and 'copper' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:38
S125	0	@ad<="20031022" and 'conductor' same 'polyvinylidene diflouride'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/04 08:38
S126	1	@ad<="20031022" and 'copper' with 'polyvinylidene' and 'PCB'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/05 07:43